RENESAS

PCN#: [EPO-EX-25-0222]

Product Change Notice (PCN)

Subject: Notice of Change of Lead Frame for RX100/200 Series LFQFP Package Products

Publication Date: 11/27/2025
Effective Date: 6/1/2026
Revision Description: Initial release

Description of Change:
Applicable products: RX111/RX130/RX230/RX231 Group LFQFP-64/80/100 pin products.
The back-end factory: Renesas Semiconductor (Beijing) Co., Ltd
Changes: The lead frame will be changed.

Affected Product List:
Refer to the Product List in the appendix below.

Reason for Change:
To ensure a stable supply.

Impact on Fit, Form, Function, Quality & Reliability:
This change will not affect fit, form, function, quality, and reliability.

Product Identification:
Our production history data can be queried by using the trace code of the product.

Qualification Status:
The reliability test has been completed. Please refer to the attached supplementary materials.

Sample Availability Date: 6/1/2026
Any requests for samples must be received by 3/31/2026.
Please contact Renesas sales, distributor, or agency.

Device Material Declaration:
Please contact our sales representatives or distributors.

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.

2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.

3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact your Renesas sales representative.

Appendix: Product List

No.	Part Number	Package Type	No. of Pins
1	R5F51117ADFK#1A	LQFP	64
2	R5F51117ADFK#3A	LQFP	64
3	R5F51117ADFK#5A	LQFP	64
4	R5F51118ADFK#1A	LQFP	64
5	R5F51118ADFK#3A	LQFP	64
6	R5F51118ADFK#5A	LQFP	64
7	R5F51306BDFK#10	LQFP	64
8	R5F51306BDFK#30	LQFP	64
9	R5F51306BDFK#50	LQFP	64
10	R5F51307ADFK#10	LQFP	64
11	R5F51307ADFK#30	LQFP	64
12	R5F51307ADFK#50	LQFP	64
13	R5F51308ADFK#10	LQFP	64
14	R5F51308ADFK#30	LQFP	64
15	R5F51308ADFK#50	LQFP	64
16	R5F51306BDFN#10	LFQFP	80
17	R5F51306BDFN#30	LFQFP	80
18	R5F51306BDFN#50	LFQFP	80
19	R5F51307ADFN#10	LFQFP	80
20	R5F51307ADFN#30	LFQFP	80
21	R5F51307ADFN#50	LFQFP	80
22	R5F51308ADFN#10	LFQFP	80
23	R5F51308ADFN#30	LFQFP	80
24	R5F51308ADFN#50	LFQFP	80
25	R5F51305BDFP#10	LFQFP	100
26	R5F51305BDFP#30	LFQFP	100
27	R5F51305BDFP#50	LFQFP	100
28	R5F51306BDFP#10	LFQFP	100
29	R5F51306BDFP#30	LFQFP	100
30	R5F51306BDFP#50	LFQFP	100
31	R5F51307ADFP#10	LFQFP	100
32	R5F51307ADFP#30	LFQFP	100
33	R5F51307ADFP#50	LFQFP	100
34	R5F51308ADFP#10	LFQFP	100
35	R5F51308ADFP#30	LFQFP	100
36	R5F51308ADFP#50	LFQFP	100
37	R5F52305ADFP#10	LFQFP	100
38	R5F52305ADFP#30	LFQFP	100
39	R5F52305ADFP#50	LFQFP	100
40	R5F52306ADFP#10	LFQFP	100
41	R5F52306ADFP#30	LFQFP	100
42	R5F52306ADFP#50	LFQFP	100
43	R5F52315CDFP#10	LFQFP	100
44	R5F52315CDFP#30	LFQFP	100
45	R5F52315CDFP#50	LFQFP	100
46	R5F52316CDFP#10	LFQFP	100
47	R5F52316CDFP#30	LFQFP	100
48	R5F52316CDFP#50	LFQFP	100

• **Appendix** : [EPO-EX-25-0222]

1. Overview of Changed Materials

Item		Before Change	After Change	Note
Assembly factory		Renesas Semiconductor (Beijing) Co., Ltd		–
Final test factory				–
	Lead frame	Lead frame A	Lead frame B (However, the material is same)	–
	Die bond	–	No change	–
	Mold resin (resin materials)	–	No change	–
Package	Outline	–	No change	–
Marking	Font	–	No change	–

＊ There will be no impact on product's reliability and specification.

2. 4M changing points （Modification and addition of assembly process members)

Item	Check result	Judgement
Machine	It is the same as the current product.	No risk
Method	It is the same as the current product.	No risk
Man	It is the same as the current product.	No risk
Material	We will only use certified materials. We have also conducted reliability tests equivalent to those of current products for finished products. We have confirmed that there is no problem.	No risk

3. Reliability Test Results

Test Items	Test Conditions	ResultsFailure/Size
High Temperature Operating Life(HTOL)	Ta=125 ℃, Vccmax, 1000 hrs	0/22
High Temperature Storage Life(HTSL)	Ta=150 ℃, 1000 hrs	0/22
Temperature Humidity bias(THB) (*1)	Ta=85 ℃, RH=85 %, Vccmax, 1000 hrs	0/22
Temperature Cycling(TC) (*1)	Ta=-65 ℃ to 150 ℃, 300 cycles	0/22
Latch-Up(LU)	Pulse Current Injection, I=+/-150 mA	0/3
Electrostatic discharge(ESD-HBM)	1.5 kΩ, 100 pF, +/-2000 V, 1 time	0/3
Electrostatic discharge(ESD-CDM)	+/-1000V,1time	0/3
Solderability(SD)	245 ℃, 5 s, Solder coverage ≥95 %	0/5
Resistance to Soldering Heat(PC)	MSL3(Moisture Sensitivity Level 3)	0/22

*1) Preprocessing of MSL3 was applied to THB and TC.

・It is tested to confirm that all the samples are satisfied with an individual product specification.

・Basically qualification tests were performed using a representative product with the same wafer process and the same package structure .